



Technical Introduction

The thermal performance of Heat Dissipating Enclosures depends on the thermal conductivity of the material from which they are made, size of surface area and mass.

In addition, mounting position, temperature, ambient air velocity and mounting place all have varying influence on the final performance of the Heat Dissipating Enclosure from one application to another.

There are no agreed international standard methods for testing electronic cooling systems or for the determination of the thermal resistance.

Therefore the diagrams and values have been determined under practical operating conditions. All information and data is given to the best of our knowledge. The user is solely responsible for the proper use of our products and should check suitability for the intended application.

The values indicated in the diagrams apply only for Heat Dissipating Enclosure mounted vertically and natural convection. Correction factors: horizontal mounting = +15% $^{\circ}\text{C}/\text{W}$ value.